Evactron® C

RF Plasma Activated Cleaning Device for Electron Microscopes and Vacuum Chambers

Evactron C De-Contaminator

XEI Scientific Evactron® C D-C is the most cost effecient and simple cleaning system. It has dual cleaning modes of plasma ashing or N2 purge. The Oxygen Radical Source (ORS) uses air for remote, low power RF plasma ashing of organics from chamber and is mounted on chamber port. Ashing is a chemical etch using O radicals (atoms) done at 300 milli-Torr (40 Pascal) and is X-ray window safe. RF generator is feedback stabilized and harmonically suppressed.

Try the Evactron® Process in your lab, free, [shipping charges apply] for 30 days by placing an evaluation PO by January 15, 2008.

Gentle, Fast, Convenient and Effective Cleaning

Evactron® De-Contaminator Model C includes:

- **RF Plasma Oxygen Radical Source (ORS), Controller/RF Generator**
- **Pirani Vacuum Gauge**
- **0 - 20 Watt RF Generator @ 13.56 MHz**
- **Air bleed Needle Valve for manual flow and pressure adjustment**
- **Bundled cable set, instructions and power cord**
- **Free 5 year limited warranty and factory service**
- **Fixed RF Match**
- **KF 40 vacuum mounting flange**
- **High Vacuum interlock**
- **RF power interlock prevents starting without air bleed open**
- **100-240 VAC 50/60 Hz, 150 Watt input**
- **CE, RoHS**
- **Shipping-22 lbs. (10 kgrms)**

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